



梅州市中联精密电子有限公司  
MEIZHOU CHINA UNITE ELECTRONIC CO., LTD

Material Composition Declaration  
PCB材料成分表

Supplier company (供应商公司名称): MEIZHOU CHINA UNITE ELECTRONIC CO.,LTD (梅州市中联精密电子有限公司)

No.	Name of the part 構成部件	Component weight(gram)100% in total product 元件佔產品重量百分比	Materials analysis(element) 構成元素分析	CAS number CAS 編號	Element Mass(gram) 元素重量(克)	Element Mass(% Weight) 元素重量(百分比)	% Weight in componet 元件重量百分比
1	copper clad laminates 覆铜箔层压板	90%	Fibrous Glass 玻璃纤维布	NO. 65997-17-3	41-44	41-44%	37-39%
			Epoxy Resin 环氧树脂	NO. 26265-08-7	37-40	37-40%	33-36%
			Copper 铜箔	NO. 7440-50-8	15-17	15-17%	13-15%
2	solder mask ink 阻焊油墨	7%	Acrylate Resin 压克力树脂	NA	40-50	40-50%	2.8-3.5%
			Diethylene Glycol Monoethyl ether acetate乙酸卡必醇	NA	10-15	10-15%	0.7-1%
			NAPHTHA 石油脑	NA	5-10	5-10%	0.35-0.7%
			water 水分	NA	35-40	35-40%	2.5-2.8%
3	character ink 文字油墨	2%	Epoxy Resin 环氧树脂	NA	50-60	50-60%	1-1.2%
			Ethylene Glycol Monobutyl aether 乙二醇单丁醚	NA	25-35	25-35%	0.05-0.07%
			water 水分	NA	20-30	20-30%	0.04-0.06%
4	OSP 抗氧化剂	1%	alkyl benzimidazole 烷基苯并咪唑	NA	10-15	10-15%	0.1-0.15%
			organic acid 有机酸	NA	20-50	20-50%	0.2-0.5%
			water 水分	NA	25-35	25-35%	0.25-0.35%
5	Free-lead tin 无铅锡	1%	Tin 锡	NA	99.9	99.90%	0.99%
			Other 其他	NA	0.1	0.10%	0.00%
6	Ni/Au 镍金	1%	nickel 镍	NA	80	80%	0.80%
			gold 金	NA	15	15%	0.15%
			Other 其他	NA	5	5%	0.05%